

ABSTRACT

A semiconductor device includes a base substrate including a base wiring pattern. A first circuit substrate is disposed over the base substrate and includes a first wiring pattern. A first semiconductor element is mounted on the first circuit substrate and includes a first electrode that is electrically connected to the first wiring pattern. A second circuit substrate is disposed over the first circuit substrate and includes a second wiring pattern and a second semiconductor element is mounted on the second circuit substrate and includes a second electrode that is electrically connected to the second wiring pattern. A first protruded electrode is electrically connected to the first wiring pattern and provided protruding from the first circuit substrate and bonded to the base wiring pattern and a second protruded electrode is electrically connected to the second wiring pattern and provided protruding from the second circuit substrate and bonded to the base wiring pattern.